

**Product Summary**

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
50V	1.0Ω@10V	0.22A
	1.1Ω@4.5V	

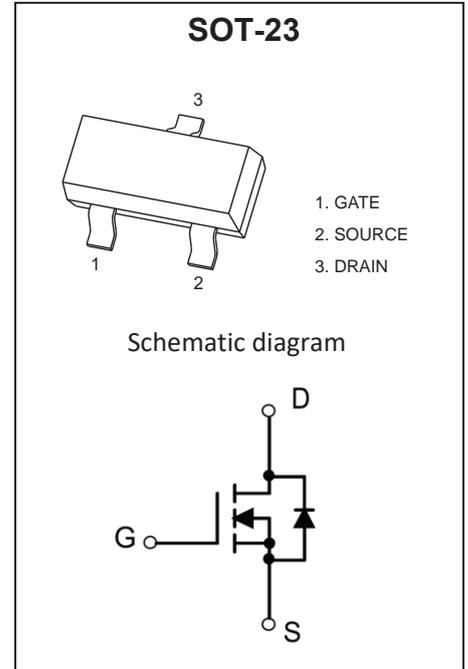
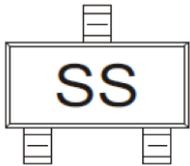
**Feature**

- High density cell design for extremely low  $R_{DS(on)}$
- Rugged and Reliable

**Application**

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays

**MARKING:**



**ABSOLUTE MAXIMUM RATINGS ( $T_a=25^{\circ}C$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	50	V
Gate-Source Voltage	$V_{GS}$	±20	
Continuous Drain Current	$I_D$	0.22	A
Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	357	$^{\circ}C/W$
Junction Temperature	$T_J$	150	$^{\circ}C$
Storage Temperature	$T_{STG}$	-55~ +150	

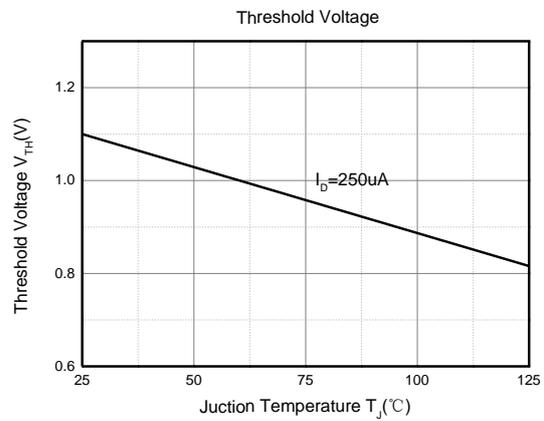
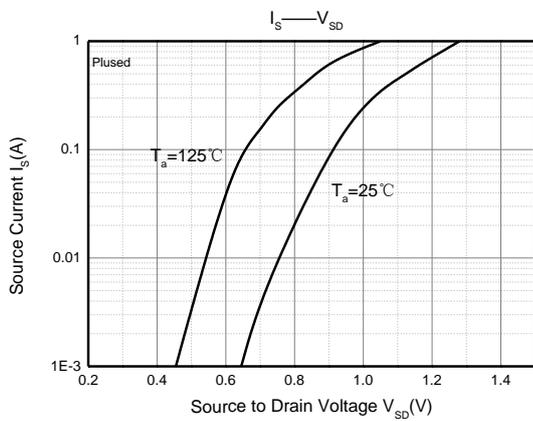
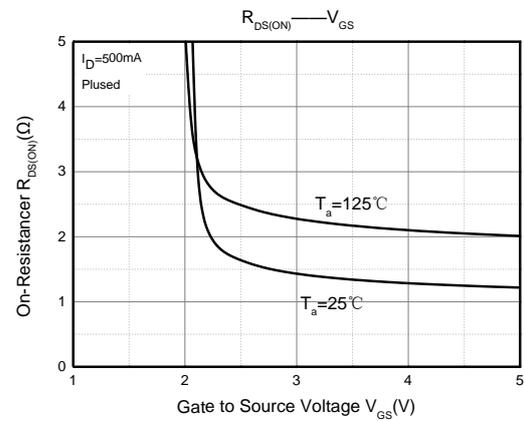
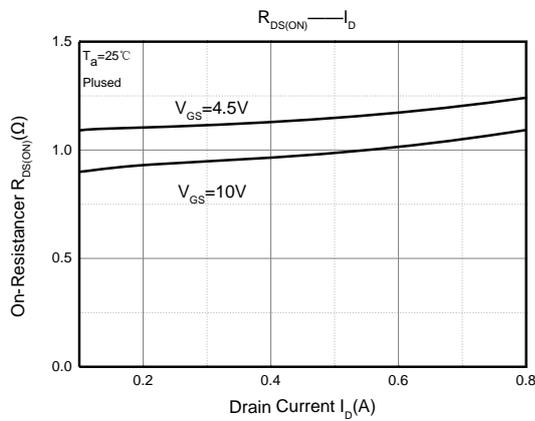
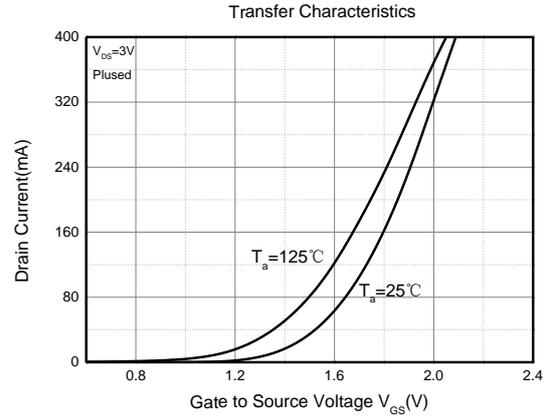
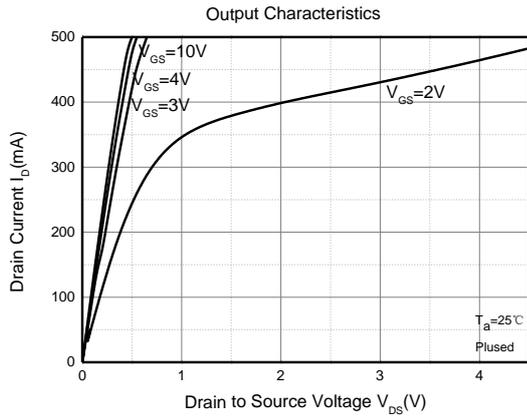
**MOSFET ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25°C unless otherwise noted)**

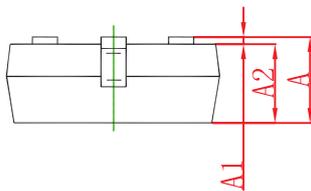
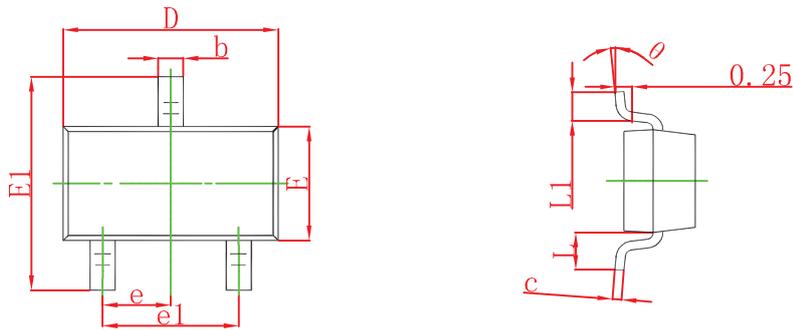
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	50			V
Zero gate voltage drain current	I <sub>DSS1</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V			0.5	μA
	I <sub>DSS2</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V			100	nA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage <sup>1</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.8		1.5	V
Drain-source on-resistance <sup>1</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.22A		1.0	3.0	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.22A		1.1	5.0	
Forward tranconductance <sup>1</sup>	g <sub>FS</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.22A		0.13		S
<b>Dynamic characteristics<sup>2</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		26.5		pF
Output Capacitance	C <sub>oss</sub>			12.9		
Reverse Transfer Capacitance	C <sub>rss</sub>			5.9		
<b>Switching Characteristics<sup>1,2</sup></b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 30V, I <sub>D</sub> = 0.29A, V <sub>GS</sub> = 10V, R <sub>G</sub> = 6Ω			5	nS
Turn-on rise time	t <sub>r</sub>				18	
Turn-off delay time	t <sub>d(off)</sub>				36	
Turn-off fall time	t <sub>f</sub>				14	
<b>Source-Drain Diode characteristics<sup>1</sup></b>						
Diode Forward voltage	V <sub>SD</sub>	I <sub>S</sub> = 0.44A, V <sub>GS</sub> = 0V		1.15	1.4	V

**Notes:**

1. Pulse Test ; Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
2. These parameters have no way to verify.

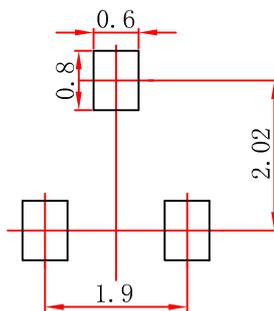
## Typical Electrical and Thermal Characteristics





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
theta	0°	8°	0°	8°

### SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.